

## ISTFA 2000: proceedings of the 26th International Symposium for Testing and Failure Analysis, 12-16 November 2000, Meydenbauer Convention Center, Bellevue, Washington

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### Abstrak

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- Laser Voltage Probe (LVP): A Novel Optical Probing Technology for Flip-Chip Packaged Microprocessors
- Scanning Electron Acoustic Microscopy: A Novel Tool for Failure Analysis & Microcharacterisation
- Application of Single Contact Optical Beam Induced Currents (SCOBIC) for Backside Failure Analysis
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